

REMARKS

In the final Office Action dated September 25, 2006, claims 1-34 were allowed and claims 35 and 36 were rejected under 35 U.S.C. 103(a) as unpatentable over U.S. Patent 6,538,313 to Smith et al. in view of patent application publication 2002/0056894 to Kuo et al. A correction was also requested for a typographical error in claim 36.

Claim 36 has been amended as requested by the Examiner. Entry of this amendment at this time is believed appropriate as it puts claim 36 in better condition for appeal.

The Examiner's indication that claims 1-34 are allowable is greatly appreciated.

The Examiner is respectfully requested to reconsider the finality of the rejection of claims 35 and 36. Claims 35 and 36 are rewritten versions of claims 14 and 30 in independent form. Claims 14 and 30 were indicated in the previous office action to be allowable if rewritten in independent form. Thus, applicant's amendment to add claims 35 and 36 to the application cannot be said to have necessitated the new ground of rejection.

Claim 35 is directed to a semiconductor package comprising:

a die;

a wire bonding package under the die and including a die attach pad with an expansion slot and lead fingers surrounding the pad;

a plurality of wire bonds connecting the die to the lead fingers;

a bottom plate under the die attach pad; and

an insulator set between the die attach pad and the bottom plate.

Claim 36 is similar and is directed to a method of assembling a semiconductor package having these elements including a die attach pad with an expansion slot.

Smith discloses a semiconductor package including a die attach pad; but as the Examiner concedes, Smith does not disclose a die attach pad having an expansion slot. Instead, the

Examiner relies on Kuo for teaching a package wherein the die attach pad has slots that “would have performed the function of ‘expansion slots’.” Applicants respectfully disagree.

The slots in question are slots 511-516, 811-814 and 911-912 in the Kuo publication. These slots are used to confine solder paste to region 517 in the embodiment shown in Fig. 3, to region 815 in the embodiment of Fig. 5 and to region 913 in the embodiment of Fig. 6. Apparently, as explained in paragraph 0016 of the Kuo publication, the cohesion of the solder paste is such that it will not flow into the slots.

The Examiner offers no explanation in support of her assertion that the slots of Kuo “would have performed the function of ‘expansion slots’.” The only function for these slots that is described by Kuo is to confine the solder paste. In the absence of any teaching or suggestion by Kuo and the absence of any explanation by the Examiner, there is no basis for the Examiner’s assertion that the slots of Kuo would have functioned as expansion slots.

Further, there is no suggestion in either Smith or Kuo that the two references should be combined. While Smith does contemplate at Col. 3, lines 16-22 the use of solder to mount a die as the Examiner notes, there is no indication in Smith that solder flow is a problem and no incentive to do anything to address such a problem. Thus, there is no suggestion that Smith be combined with some other reference.

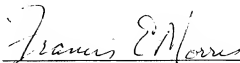
Accordingly, it is respectfully submitted that claims 35 and 36 are patentable over the references.

No additional fee is believed to be due for filing this response. However, if a fee is due, please charge such fee to Morgan, Lewis & Bockius LLP Deposit Account No. 50-0310.

If the Examiner believes a telephone interview would expedite prosecution of this application, she is invited to call applicant's attorney at the number given below.

Date: November 20, 2006

Respectfully submitted,

A handwritten signature in cursive script, reading "Francis E. Morris", written in dark ink.

Francis E. Morris

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